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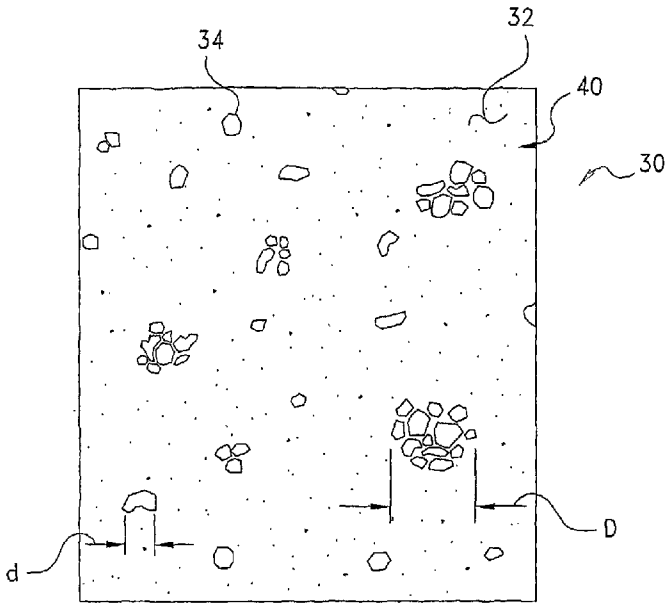
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(54) Title: THERMAL MANAGEMENT MATERIALS



(57) Abstract: A thermally-conductive compound for forming a layer which is conformable between a first heat transfer surface and an opposing second heat transfer surface to provide a thermal pathway therebetween. The compound is an admixture of a thermal grease component and a dispersed constituent forming discrete domains within the grease component, the domains being form-stable at normal room temperature in a first phase and conformable between the first and second heat transfer surface in a second phase, and the domains having a domain transition temperature above normal room temperature from the first phase to the second phase. The dispersed constituent may be a fusible, i.e., low temperature melting, metal or metal alloy.

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